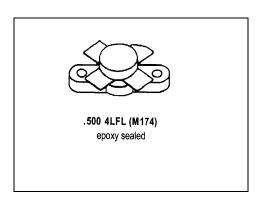


MS1076

RF & MICROWAVE TRANSISTORS HF SSB APPLICATIONS

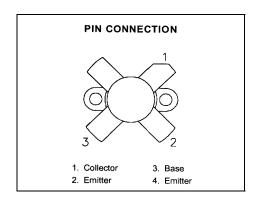
Features

- 30 MHz
- 28 VOLTS
- GOLD METALLIZATION
- P_{OUT} = 220 W PEP
- G_P = 12 dB GAIN MINIMUM
- COMMON EMITTER CONFIGURATION



DESCRIPTION:

The MS1076 is a 28 volt epitaxial NPN silicon planar transistor designed primarily for SSB and VHF communications. This device utilizes an emitter ballasted die geometry for maximum ruggedness and reliability.



ABSOLUTE MAXIMUM RATINGS (Tcase = 25°C)

Symbol	Parameter	Value	Unit
V _{CBO}	Collector - Base Voltage	70	V
V _{CEO}	Collector - Emitter Voltage	35	V
V _{EBO}	Emitter - Base Voltage	4.0	V
I c	Device Current	16	Α
P _{DISS}	Power Dissipation	250	W
Τ _J	Junction Temperature	+200	°C
T _{STG}	Storage Temperature	- 65 to +150	°C

Thermal Data

R _{TH(J-C)}	Junction - Case Thermal Resistance	0.7	°C/W
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Rev A: October 2009



MS1076

ELECTRICAL SPECIFICATIONS (Tcase = 25°C) STATIC

Symbol	Test Conditions	Value			
		Min.	Тур.	Max.	Unit
BV _{CES}	I _C = 100 mA	70			V
BV _{CEO}	I _C = 200 mA	35			V
BV _{EBO}	I _E = 20 mA	4.0			V
I _{CEO}	V _{CE} = 30 V			5	mA
I _{CES}	V _{CE} = 35 V			5	mA
H _{FE}	$V_{CE} = 5 V$, $I_C = 7 A$	15		60	

DYNAMIC

Symbol		Test Condition	ns	Value			
				Min.	Typ.	Max.	Unit
P _{out}	f = 30 MHz	$V_{CE} = 28 \text{ V}$	$I_{CQ} = 750 \text{ mA}$	220			WPEP
G _P	f = 30 MHz	V _{CE} = 28 V	I _{CQ} = 750 mA	12			dB
ης	f = 30 MHz	V _{CE} = 28 V	I _{CQ} = 750 mA	40			%
IMD	f = 30 MHz	V _{CE} = 28 V	I _{CQ} = 750 mA			-30	dBc
Сов	f = 1 MHz	V _{CB} = 28 V			450		pf
Conditions	f1 = 30.000 MHz	f2 = 30.001 M	Hz				

HFE BINNING (marked on lid with appropriate letter):

A = 15-19	D = 27-32	G = 45-50
B = 19-22.5	E = 32-38	H = 50-55
C = 22.5-27	F = 38-45	I = 55-60

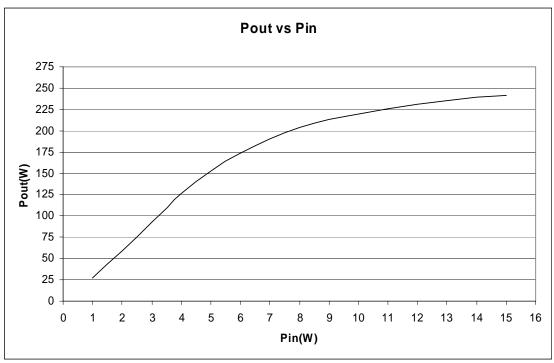
IMPEDANCE DATA

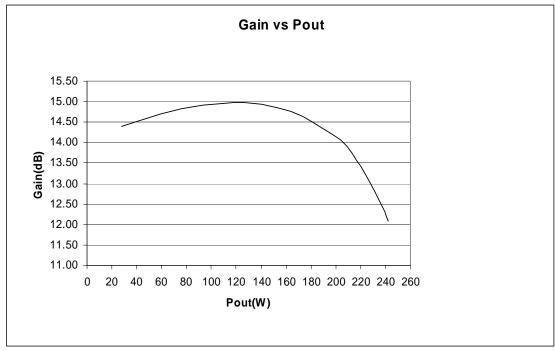
FREQ	Z _{IN}	Z _{CL}		
30 MHz	1.2 + j0.41	1.25 + j1.92		





TYPICAL PERFORMANCE





Microsemi reserves the right to change, without notice, the specifications and information contained herein.

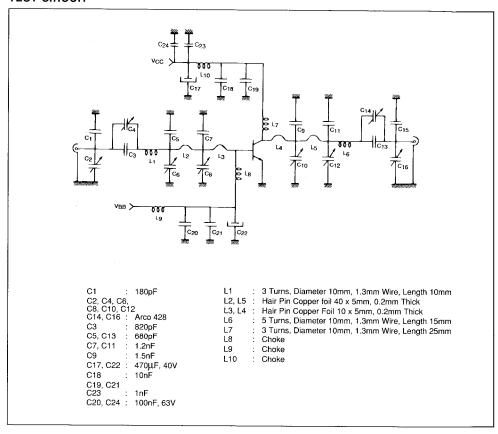
Visit our web site at www.microsemi.com or contact our factory direct.

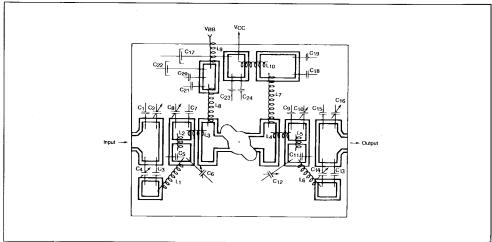




TEST CIRCUIT

TEST CIRCUIT

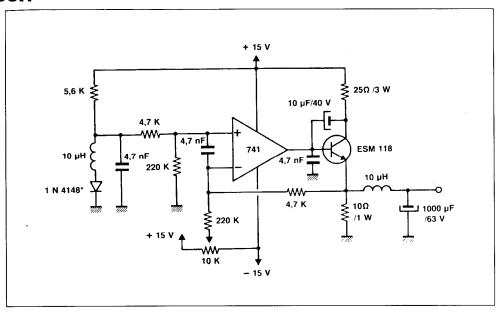








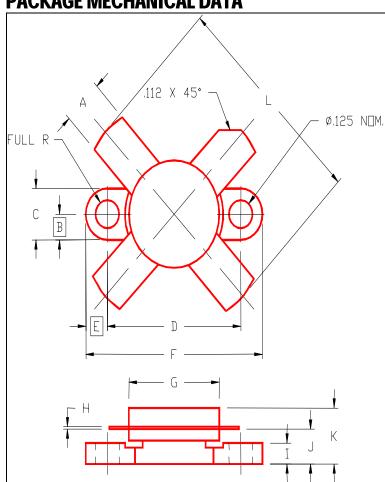
BIAS CIRCUIT





MS1076

PACKAGE MECHANICAL DATA



PACKAGE STYLE M174

	MINIMUM	MUMIXAM		MINIMUM	MAXIMUM
	INCHES/MM	INCHES/MM		INCHES/MM	INCHES/MM
Α	.220/5,59	,230/5,84	I	.090/2,29	.110/2,79
В	.125	′ 3,18	J	.160/4,06	.175/4,45
С	,245/6,22	,255/6,48	К		.280/7,11
D	.720/18,28	.730/18,54	L		1.050/26,67
Ε	.125/3,18				
F	.970/24,64	.980/24,89			
G	.495/12,57	.505/12,83			
Н	.003/0,08	.007/0,18			